Book Review

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Editors: J.C. Gelpey, M.C. Öztürk, R.P.S. Thakur, A.T. Fiory, F. Roozeboom
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Reviewed By: John Ogren

This is a valuable collection of papers from a recent symposium devoted to the use of rapid thermal techniques in the processing of microelectronics components. Most of the papers deal with processing silicon-based electronics although several papers deal with sol-gel processing.

Nothing in this particular volume concerns processing of steel, aluminum, or other metallurgical products.

The general view is that Rapid Isothermal Processing (RIP), based on incoherent radiation as a source of both optical and thermal energy, will play a major role in designing new semiconductor processing equipment in the next few years. The major advantages are tighter process control, lower thermal budgets and higher yields through lower concentration of microscopic defects.

The volume includes numerous papers on the properties of a large variety of microelectronics devices made by a large variety of processing machines using the RIP approach.

The book is a valuable volume for everyone actively engaged in the processing of silicon-based devices.